

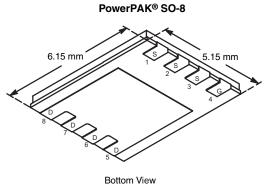
RoHS

COMPLIANT

Vishay Siliconix

N-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	r _{DS(on)} (Ω)	I _D (A)				
100	0.034 @ V _{GS} = 10 V	7.8				
	0.040 @ $V_{GS} = 6.0 V$	7.2				



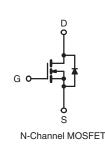
Ordering Information: Si7454DP-T1 Si7454DP-T1-E3 (Lead (Pb)-Free)

FEATURES

- TrenchFET[®] Power MOSFETS
- New Low Thermal Resistance PowerPAK® Package with Low 1.07-mm Profile
- PWM Optimized for Fast Switching
- 100 % R_g Tested

APPLICATIONS

- Primary Side Switch for High Density DC/DC
- Telecom/Server 48-V, Full-/Half-Bridge DC/DC
- Industrial and 42-V Automotive



ABSOLUTE MAXIMUM RATINGS T_A = 25 °C, unless otherwise noted Parameter Symbol 10 secs **Steady State** Unit Drain-Source Voltage V_{DS} 100 v V_{GS} Gate-Source Voltage ±20 7.8 5.0 T_A = 25°C Continuous Drain Current (T_J = 150°C)^a I_D T_A = 85°C 5.7 3.6 Α Pulsed Drain Current 30 I_{DM} Avalanche Current Ī_{AS} 25 L = 0.1 mHE_{AS} Single Avalanche Energy (Duty Cycle \leq 1 %) 31 mJ 4.0 1.6 А Continuous Source Current (Diode Conduction)^a Is 4.8 1.9 $T_A = 25^{\circ}C$ Maximum Power Dissipation^a P_D W $T_A = 85^{\circ}C$ 2.6 1.0 Operating Junction and Storage Temperature Range T_J, T_{stg} -55 to 150 °C 260 Soldering Recommendations (Peak Temperature)^{b,c}

THERMAL RESISTANCE BATINGS

Parameter		Symbol	Typical	Maximum	Unit				
Manimum lugation to Ambianta	$t \le 10 \text{ sec}$	– R _{thJA}	21	26					
Maximum Junction-to-Ambient ^a	Steady State		55	65	°C/W				
Maximum Junction-to-Case (Drain) Steady State		R _{thJC}	1.6	2					

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

b. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection. c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

* Pb containing terminations are not RoHS compliant, exemptions may apply

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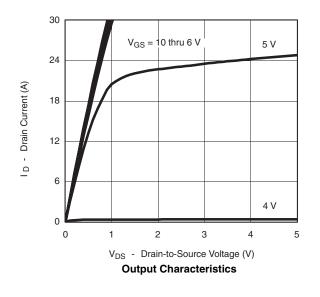


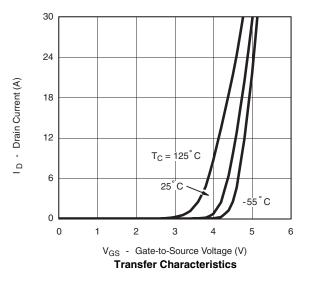
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit	
Static					1		
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2		4	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			±100	nA	
7	I _{DSS}	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA	
Zero Gate Voltage Drain Current		$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85^{\circ}\text{C}$			20		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5$ V, V_{GS} = 10 V	30			А	
Drain-Source On-State Resistance ^a		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 7.8 \text{ A}$		0.028	0.034	0	
	r _{DS(on)}	$V_{GS} = 6.0 \text{ V}, I_{D} = 7.2 \text{ A}$		0.032	0.040	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 7.8 A		25		S	
Diode Forward Voltage ^a	V _{SD}	$I_{S} = 4 A, V_{GS} = 0 V$		0.8	1.2	V	
Dynamic ^b	L						
Total Gate Charge	Qg	Q _q		24	30		
Gate-Source Charge	Q _{gs} Q _{gd}	V_{DS} = 50 V, V_{GS} = 10 V, I_{D} = 7.8 A		7.6		nC	
Gate-Drain Charge				5.4			
Gate Resistance	Rg		0.5	1.25	2.2	Ω	
Turn-On Delay Time	t _{d(on)}			16	30		
Rise Time t _r		V_{DD} = 50 V, R_L = 50 Ω		10	20	ns	
Turn-Off Delay Time	$t_{d(off)}$ I _D \cong 1.0 A, V _{GEN} = 10 V, R _G = 6 Ω		35	70			
Fall Time t _f				20	40		
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 4 A, di/dt = 100 A/μs		50	80	l	

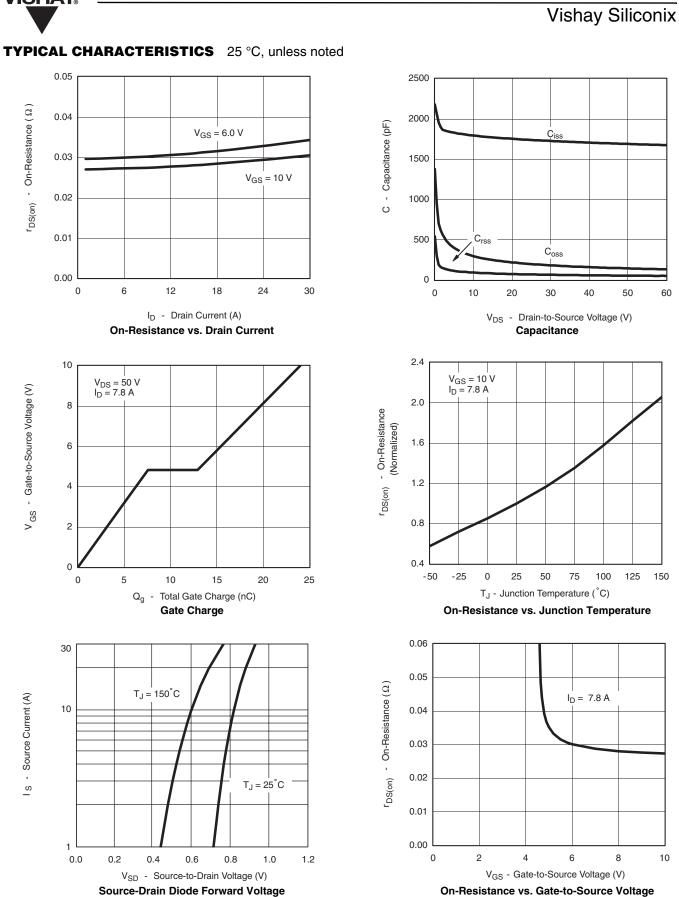
Notes a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless noted





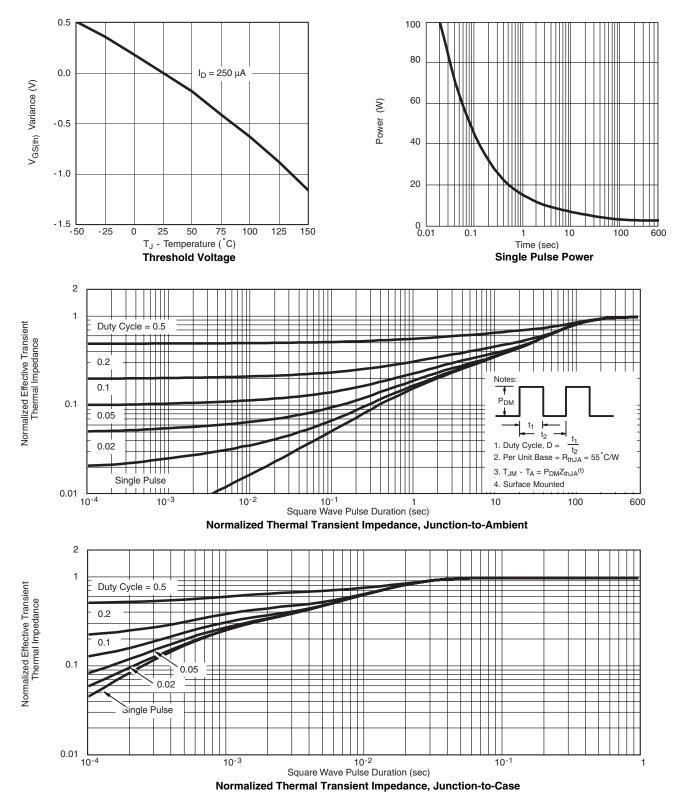


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Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?71618.





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